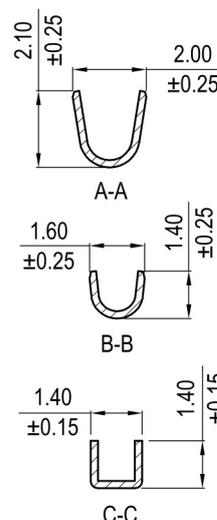
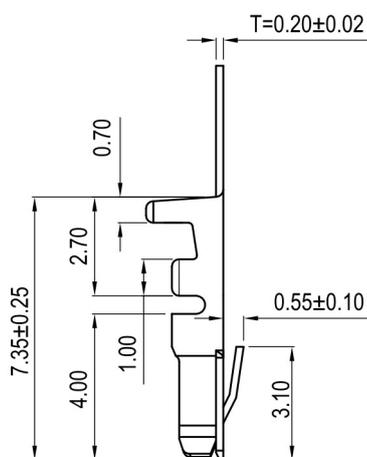
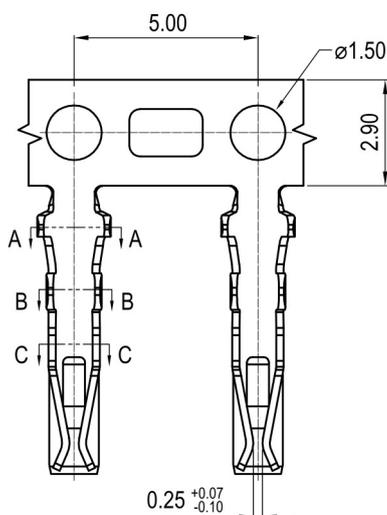
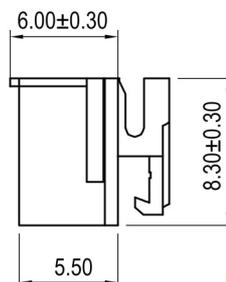
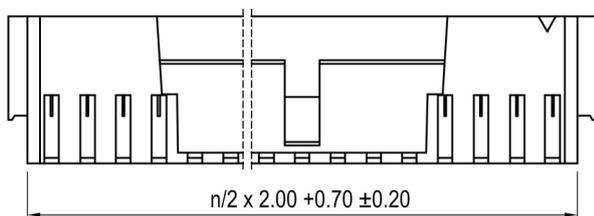
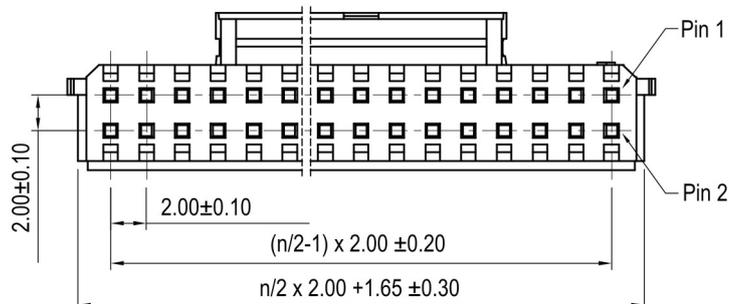
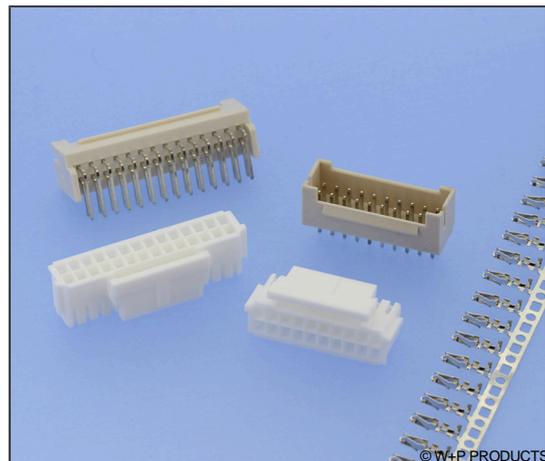


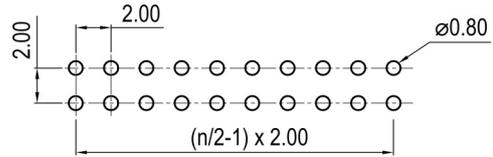
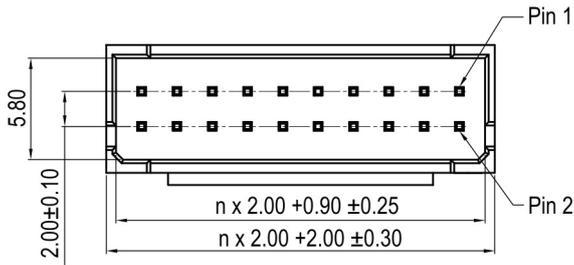
Crimp-Rast-Stift-/Buchsenleisten RM 2,00mm, gerade/gewinkelt, mit Verriegelung

Friction Lock Headers / Crimp-Housings, 2.00mm Pitch, Straight/Right-Angled, Locking Type

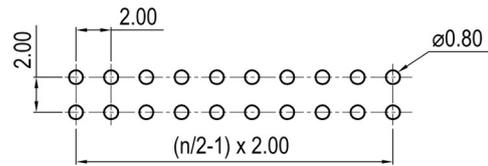
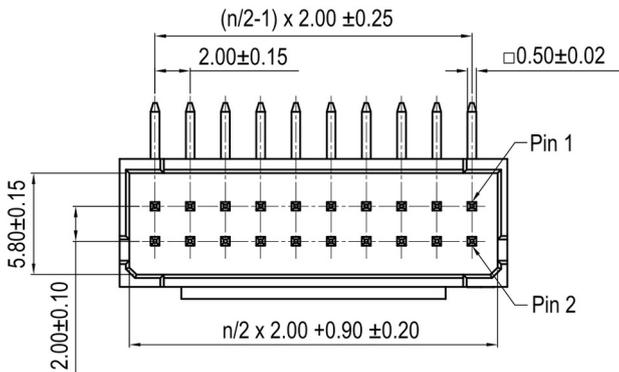
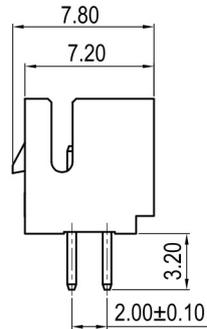
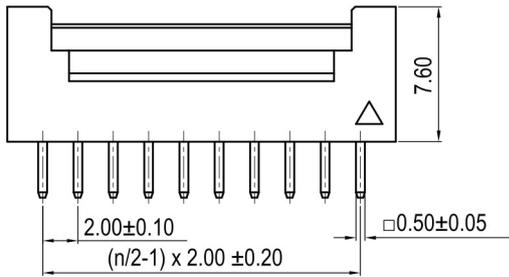
Technische Daten / Technical Data

Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Vierkantstift 0,50mm, Kupferlegierung
Contact Material	0.50mm square pin, copper alloy
Aderquerschnitt	AWG 28 ~ 22
Applicable wire Gauge	AWG 28 ~ 22
Durchgangswiderstand	< 20 mΩ
Contact Resistance	< 20 mΩ
Isolationswiderstand	> 1000 MΩ
Insulation Resistance	> 1000 MΩ
Spannungsfestigkeit	1000 V AC
Test Voltage	1000 V AC
Nennspannung	250 V AC
Voltage Rating	250 V AC
Nennstrom	3 A
Current Rating	3 A
Temperaturbereich	-25 °C ... +85 °C
Temperature Range	-25 °C ... +85 °C
Verarbeitung	Wellenlötverfahren
Processing	Wave soldering

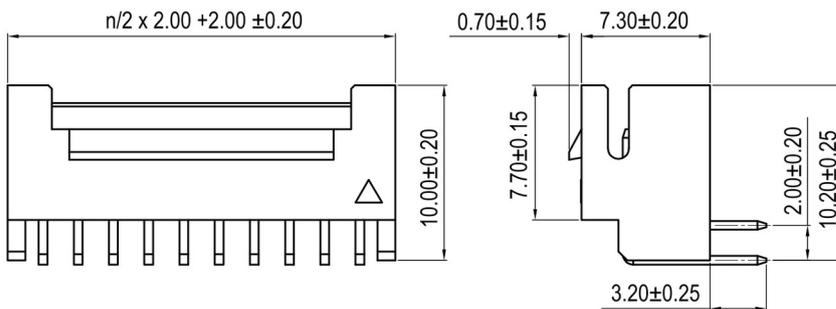




Recommended PCB Layout



Recommended PCB Layout



Serie

548

Contacts*

12

01 (Für Buchsenkontakte)
(For female terminals)
04-40

Type*

1

1 Buchsengehäuse
Female housing
2 Buchsenkontakte (AWG 22-28)
Female terminals (AWG 22-28)
3 Wannenstiftleiste gerade
Box header straight
4 Wannenstiftleiste gewinkelt
Box header right-angled

Plating

50

50 Verzinkt (für Gehäuse nicht erforderlich)
Tin plated (not needed for housings)

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Empfehlungen für das Wellenlötverfahren

Recommendations for Wave Soldering

Die Bauteile sollten bei einer Lötbadtemperatur von 260°C in max. 5 Sekunden verlötet werden.

Empfohlenes Wellenlötprofil:

